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Clear	Generate Collection	Print	Fwd Refs	Bkwd Refs
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Search Results - Record(s) 1 through 10 of 10 returned.

☐ 1. Document ID: US 20040079393 A1

L4: Entry 1 of 10

File: PGPB

Apr 29, 2004

PGPUB-DOCUMENT-NUMBER: 20040079393

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20040079393 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 29, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Klispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/22.19; 134/22.1, 134/24, 134/27

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution. The chelating agent solution removes metallic contamination from the containers. The containers are then rinsed with a rinsing liquid, such as deionized water and a surfactant. The containers are then dried, preferably by applying heat and/or hot air movement.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw. De
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☐ 2. Document ID: US 20030216049 A1

L4: Entry 2 of 10

File: PGPB

Nov 20, 2003

PGPUB-DOCUMENT-NUMBER: 20030216049
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20030216049 A1

TITLE: Method and composition for the removal of residual materials during substrate planarization

PUBLICATION-DATE: November 20, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Sun, Lizhong	San Jose	CA	US	
Tsai, Stan D.	Fremont	CA	US	
Li, Shijian	San Jose	CA	US	

US-CL-CURRENT: 438/697

ABSTRACT:

A method, composition, and computer readable medium for planarizing a substrate. In one aspect, the composition includes one or more chelating agents and ions of at least one transition metal, one or more surfactants, one or more oxidizers, one or more corrosion inhibitors, and deionized water. The composition may further comprise one or more agents to adjust the pH and/or abrasive particles. The method comprises planarizing a substrate using a composition including one or more chelating agents and ions of at least one transition metal. In one aspect, the method comprises processing a substrate disposed on a polishing pad including performing a first polishing process to substantially remove the copper containing material, performing a second polishing process to remove residual copper containing material, the second polishing process comprising delivering a CMP composition to the polishing pad, mixing one or more chelating agents and ions of at least one transition metal in situ with the CMP composition, and removing residual copper containing materials from the substrate surface. The invention also provides a computer readable medium bearing instructions for planarizing a substrate surface, the instructions arranged, when executed by one or more processors, to cause one or more processors to control a system to perform polishing the substrate to substantially remove copper containing material formed thereon and polishing the substrate with a CMP composition comprising one or more chelating agents and ions of at least one transition metal to remove residual copper containing material.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Drawings
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☐ 3. Document ID: US 20030127320 A1

L4: Entry 3 of 10

File: PGPB

Jul 10, 2003

PGPUB-DOCUMENT-NUMBER: 20030127320
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20030127320 A1

TITLE: Apparatus for electrochemically depositing a material onto a workpiece surface

PUBLICATION-DATE: July 10, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Emesh, Ismail	Gilbert	AZ	US	
Chadda, Saket	Phoenix	AZ	US	

US-CL-CURRENT: 204/207; 204/209, 204/227

ABSTRACT:

A multi-process workpiece apparatus is disclosed. The multi-process workpiece apparatus includes an electrochemical deposition apparatus which has a wafer contacting surface having at least one electrical conductor disposed therein. The multi-process workpiece apparatus also includes a planarization apparatus and at least one workpiece handling robot configured to transport a workpiece from the electrochemical deposition apparatus to the planarization apparatus.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw De
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4. Document ID: US 20030062069 A1

L4: Entry 4 of 10

File: PGPB

Apr 3, 2003

PGPUB-DOCUMENT-NUMBER: 20030062069

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030062069 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 3, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution. The chelating agent solution removes metallic contamination from the containers. The containers are then rinsed with a rinsing liquid, such as deionized water and a surfactant. The containers are then dried, preferably by applying heat and/or hot air movement.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMC	Draw D
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☐ 5. Document ID: US 20030051743 A1

L4: Entry 5 of 10

File: PGPB

Mar 20, 2003

PGPUB-DOCUMENT-NUMBER: 20030051743
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20030051743 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: March 20, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a loader of a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution, while the rotor is spinning. The chelating agent solution removes metallic contamination from the containers. The containers are then sprayed with a rinsing liquid, such as deionized water and a surfactant while the rotor is spinning and heat is applied. The containers are then dried by applying heat, hot air movement and spinning the rotor.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMC	Draw D
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☐ 6. Document ID: US 20020068454 A1

L4: Entry 6 of 10

File: PGPB

Jun 6, 2002

PGPUB-DOCUMENT-NUMBER: 20020068454
PGPUB-FILING-TYPE: new
DOCUMENT-IDENTIFIER: US 20020068454 A1

TITLE: Method and composition for the removal of residual materials during substrate planarization

PUBLICATION-DATE: June 6, 2002

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Sun, Lizhong	San Jose	CA	US	
Tsai, Stan	Fremont	CA	US	
Li, Shijian	San Jose	CA	US	

US-CL-CURRENT: 438/692

ABSTRACT:

A method, composition, and computer readable medium for planarizing a substrate. In one aspect, the composition includes one or more chelating agents and ions of at least one transition metal, one or more surfactants, one or more oxidizers, one or more corrosion inhibitors, and deionized water. The composition may further comprise one or more agents to adjust the pH and/or abrasive particles. The method comprises planarizing a substrate using a composition including one or more chelating agents and ions of at least one transition metal. In one aspect, the method comprises processing a substrate disposed on a polishing pad including performing a first polishing process to substantially remove the copper containing material, performing a second polishing process to remove residual copper containing material, the second polishing process comprising delivering a CMP composition to the polishing pad, mixing one or more chelating agents and ions of at least one transition metal in situ with the CMP composition, and removing residual copper containing materials from the substrate surface. The invention also provides a computer readable medium bearing instructions for planarizing a substrate surface, the instructions arranged, when executed by one or more processors, to cause one or more processors to control a system to perform polishing the substrate to substantially remove copper containing material formed thereon and polishing the substrate with a CMP composition comprising one or more chelating agents and ions of at least one transition metal to remove residual copper containing material

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMC	Draw D
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☐ 7. Document ID: US 6309532 B1

L4: Entry 7 of 10

File: USPT

Oct 30, 2001

US-PAT-NO: 6309532

DOCUMENT-IDENTIFIER: US 6309532 B1

TITLE: Method and apparatus for capacitive deionization and electrochemical purification and regeneration of electrodes

DATE-ISSUED: October 30, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Tran; Tri D.	Livermore	CA		
Farmer; Joseph C.	Tracy	CA		
Murguia; Laura	Manteca	CA		

US-CL-CURRENT: 205/687; 204/267, 204/269, 204/278.5, 204/551, 204/554, 205/688

ABSTRACT:

An electrically regeneratable electrochemical cell (30) for capacitive deionization and electrochemical purification and regeneration of electrodes includes two end plates (31, 32), one at each end of the cell (30). A new regeneration method is applied to the cell (30) which includes slowing or stopping the purification cycle, electrically desorbing contaminants and removing the desorbed contaminants. The cell (30) further includes a plurality of generally identical double-sided intermediate electrodes (37-43) that are equidistally separated from each other, between the two end electrodes (35, 36). As the electrolyte enters the cell, it flows through a continuous open serpentine channel (65-71) defined by the electrodes, substantially parallel to the surfaces of the electrodes. By polarizing the cell (30), ions are removed from the electrolyte and are held in the electric double layers formed at the carbon aerogel surfaces of the electrodes. The cell (30) is regenerated electrically to desorb such previously removed ions.

30 Claims, 41 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 26

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Drawn
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☐ 8. Document ID: US 6194317 B1

L4: Entry 8 of 10

File: USPT

Feb 27, 2001

US-PAT-NO: 6194317

DOCUMENT-IDENTIFIER: US 6194317 B1

**** See image for Certificate of Correction ****TITLE: Method of planarizing the upper surface of a semiconductor wafer

DATE-ISSUED: February 27, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kaisaki; David A.	St. Paul	MN		
Kranz; Heather K.	Blaine	MN		
Wood; Thomas E.	Stillwater	MN		
Hardy; L. Charles	St. Paul	MN		

US-CL-CURRENT: 438/692; 438/633, 438/693

ABSTRACT:

This invention pertains to a method of modifying or refining a surface of a wafer suited for semiconductor fabrication. This method may be used to modify a wafer having an unmodified, exposed surface comprised of a layer of a second material deployed over at least one discrete feature of a first material attached to the wafer. A first step of this method comprises contacting and relatively moving the exposed surface of the wafer with respect to an abrasive article, wherein the

abrasive article comprises an exposed surface of a plurality of three-dimensional abrasive composites comprising a plurality of abrasive particles fixed and dispersed in a binder and maintaining contact to effect removal of the second material. In a second step, the contact and relative motion are continued until an exposed surface of the wafer has at least one area of exposed first material and at least one area of exposed second material.

103 Claims, 7 Drawing figures
Exemplary Claim Number: 1
Number of Drawing Sheets: 3

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMIC	Draw D
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☐ 9. Document ID: US 6107166 A

L4: Entry 9 of 10

File: USPT

Aug 22, 2000

US-PAT-NO: 6107166
DOCUMENT-IDENTIFIER: US 6107166 A

TITLE: Vapor phase cleaning of alkali and alkaline earth metals

DATE-ISSUED: August 22, 2000

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Butterbaugh; Jeffery W.	Eden Prairie	MN		
Sawin; Herbert H.	Chestnut Hill	MA		
Zhang; Zhe	Irvine	CA		
Han; Yong-Pil	Boston	MA		

US-CL-CURRENT: 438/477; 134/31, 216/79, 252/79.4, 257/E21.227, 438/906, 510/175, 510/511

ABSTRACT:

A process for removing a Group I or Group II metal species from a surface of a semiconductor substrate. The process comprises exposing the surface to a gaseous reactant mixture comprising HF, a second compound and a silane compound, and removing volatile products from the surface. The invention is further directed to a process for etching oxides from a semiconductor substrate comprising exposing the surface to a gaseous reactant mixture comprising HF, a second compound and a silane compound, and removing volatile products from the surface.

25 Claims, 2 Drawing figures
Exemplary Claim Number: 24
Number of Drawing Sheets: 1

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMIC	Draw D
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10. Document ID: US 5958794 A

L4: Entry 10 of 10

File: USPT

Sep 28, 1999

US-PAT-NO: 5958794

DOCUMENT-IDENTIFIER: US 5958794 A

TITLE: Method of modifying an exposed surface of a semiconductor wafer

DATE-ISSUED: September 28, 1999

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Bruxvoort; Wesley J.	Woodbury	MN		
Culler; Scott R.	Burnsville	MN		
Ho; Kwok-Lun	Woodbury	MN		
Kaisaki; David A.	St. Paul	MN		
Kessel; Carl R.	St. Paul	MN		
Klun; Thomas P.	Lakeland	MN		
Kranz; Heather K.	Blaine	MN		
Messner; Robert P.	St. Paul	MN		
Webb; Richard J.	Inver Grove Heights	MN		
Williams; Julia P.	St. Paul	MN		

US-CL-CURRENT: 438/692; 216/88, 257/E21.244, 451/539

ABSTRACT:

A method of modifying an exposed surface of a semiconductor wafer that includes the steps of:

(a) contacting the surface with a fixed abrasive article having a three-dimensional textured abrasive surface that includes a plurality of abrasive particles and a binder in the form of a pre-determined pattern; and

(b) relatively moving the wafer and the fixed abrasive article to modify said surface of the wafer.

60 Claims, 17 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 7

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWC	Draw. De
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Term	Documents
METAL	3862426
METALS	673862

REMOV\$	0
REMOV	56346
REMOVA	8712
REMOVAA	21
REMOVAABLE	6
REMOVAABLY	1
REMOVAAE	2
REMOVAAL	3
REMOVAALE	37
(L3 AND (METAL REMOV\$)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	10

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☐ 1. Document ID: US 20040079393 A1

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L12: Entry 1 of 5

File: PGPB

Apr 29, 2004

PGPUB-DOCUMENT-NUMBER: 20040079393

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20040079393 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 29, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/22.19; 134/22.1, 134/24, 134/27

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC	Draw De
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☐ 2. Document ID: US 20030062069 A1

L12: Entry 2 of 5

File: PGPB

Apr 3, 2003

PGPUB-DOCUMENT-NUMBER: 20030062069

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030062069 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 3, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	

Bergman, Eric J.	Kalispell	MT	US
Scranton, Dana R.	Kalispell	MT	US

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution. The chelating agent solution removes metallic contamination from the containers. The containers are then rinsed with a rinsing liquid, such as deionized water and a surfactant. The containers are then dried, preferably by applying heat and/or hot air movement.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC	Draw De
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3. Document ID: US 20030051743 A1

L12: Entry 3 of 5

File: PGPB

Mar 20, 2003

PGPUB-DOCUMENT-NUMBER: 20030051743

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030051743 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: March 20, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a loader of a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution, while the rotor is spinning. The chelating agent solution removes metallic contamination from the containers. The containers are then sprayed with a rinsing liquid, such as deionized water and a surfactant while the rotor is spinning and heat is applied. The containers are then dried by applying heat, hot air movement and spinning the rotor.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KMC	Draw De
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☐ 4. Document ID: US 6239038 B1

L12: Entry 4 of 5

File: USPT

May 29, 2001

US-PAT-NO: 6239038

DOCUMENT-IDENTIFIER: US 6239038 B1

**** See image for Certificate of Correction ****

TITLE: Method for chemical processing semiconductor wafers

DATE-ISSUED: May 29, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Wen; Ziyang	Gresham	OR	97030	

US-CL-CURRENT: 438/745

ABSTRACT:

A method and apparatus for processing semiconductor wafer blanks comprises an enclosed chamber with upper and lower plates with a plurality of fluid openings leading from a source of chemical cleaning fluids, flushing fluid and dry nitrogen gas. The top plate also acts as a vacuum chuck to hold the wafer after the top surface has been cleaned and may rotate or oscillate to enhance the cleaning of the lower wafer surface. The method includes a chemical cleaning of the wafer top followed by processing the lower surface by pumping appropriate chemicals through the lower plate center toward the wafer periphery while the wafer is extremely close to the surface so that the outward moving fluids cover the wafer surface and are sparingly used. As the chemicals flow toward the periphery, their strength is renewed by the addition of new chemicals pumped through additional holes.

20 Claims, 25 Drawing figures

Exemplary Claim Number: 1

Number of Drawing Sheets: 15

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw De
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☐ 5. Document ID: US 20040079393 A1

L12: Entry 5 of 5

File: DWPI

Apr 29, 2004

DERWENT-ACC-NO: 2004-347321

DERWENT-WEEK: 200432

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TITLE: Removal method for metallic contaminants in a wafer container by spraying inside surface of the container with a solution of a liquid including a chelating agent through liquid spray nozzles

INVENTOR: BERGMAN, E J; BREESE, R G ; BRYER, C J ; SCRANTON, D R

PRIORITY-DATA: 2002US-0224625 (August 20, 2002), 2000US-0658395 (September 8, 2000), 2002US-0200071 (July 19, 2002), 2003US-0692829 (October 23, 2003)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
US 20040079393 A1	April 29, 2004		010	B08B009/04

INT-CL (IPC): B08 B 3/00; B08 B 9/04

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KMC	Draw D
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Term	Documents
WAFER	334205
WAFERS	109487
CONTAINER	955039
CONTAINERS	317930
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☐ 1. Document ID: US 20040079393 A1

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L19: Entry 1 of 3

File: DWPI

Apr 29, 2004

DERWENT-ACC-NO: 2004-347321

DERWENT-WEEK: 200432

COPYRIGHT 2004 DERWENT INFORMATION LTD

TITLE: Removal method for metallic contaminants in a wafer container by spraying inside surface of the container with a solution of a liquid including a chelating agent through liquid spray nozzles

INVENTOR: BERGMAN, E J; BREESE, R G ; BRYER, C J ; SCRANTON, D R

PRIORITY-DATA: 2002US-0224625 (August 20, 2002), 2000US-0658395 (September 8, 2000), 2002US-0200071 (July 19, 2002), 2003US-0692829 (October 23, 2003)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
US 20040079393 A1	April 29, 2004		010	B08B009/04

INT-CL (IPC): B08 B 3/00; B08 B 9/04

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw D
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☐ 2. Document ID: US 20030062069 A1

L19: Entry 2 of 3

File: DWPI

Apr 3, 2003

DERWENT-ACC-NO: 2003-420440

DERWENT-WEEK: 200432

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TITLE: Copper contaminant removal method for semiconductor device manufacture, involves spraying wafer container with dilute chelating agent of predetermined concentration

INVENTOR: BERGMAN, E J; BREESE, R G ; BRYER, C J ; SCRANTON, D R

PRIORITY-DATA: 2002US-0224625 (August 20, 2002), 2000US-0658395 (September 8, 2000), 2002US-0200071 (July 19, 2002)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC

US 20030062069 A1

April 3, 2003

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B08B007/00

INT-CL (IPC): B08 B 7/00

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw D
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3. Document ID: US 20030051743 A1

L19: Entry 3 of 3

File: DWPI

Mar 20, 2003

DERWENT-ACC-NO: 2003-380804

DERWENT-WEEK: 200432

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TITLE: Metal removal method for wafer container, involves spraying chelating agent and rinsing liquid sequentially along rotating container and then container is dried

INVENTOR: BERGMAN, E J; BREESE, R G ; BRYER, C J ; SCRANTON, D R

PRIORITY-DATA: 2002US-0200071 (July 19, 2002), 2000US-0658395 (September 8, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
US 20030051743 A1	March 20, 2003		010	B08B007/00

INT-CL (IPC): B08 B 7/00

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw D
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Term	Documents
WAFER	345439
WAFERS	113953
CONTAINER	1162851
CONTAINERS	404686
CHELATING	65175
CHELATINGS	3
AGENT	1746461
AGENTS	919867
((CHELATING ADJ AGENT) NEAR10 (WAFER ADJ CONTAINER)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	3
((WAFER CONTAINER) NEAR10 (CHELATING AGENT)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	3

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☐ 1. Document ID: US 20040079393 A1

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L26: Entry 1 of 5

File: PGPB

Apr 29, 2004

PGPUB-DOCUMENT-NUMBER: 20040079393

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20040079393 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 29, 2004

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/22.19; 134/22.1, 134/24, 134/27

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 2. Document ID: US 20030062069 A1

L26: Entry 2 of 5

File: PGPB

Apr 3, 2003

PGPUB-DOCUMENT-NUMBER: 20030062069

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030062069 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: April 3, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	

Bergman, Eric J.	Kalispell	MT	US
Scranton, Dana R.	Kalispell	MT	US

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution. The chelating agent solution removes metallic contamination from the containers. The containers are then rinsed with a rinsing liquid, such as deionized water and a surfactant. The containers are then dried, preferably by applying heat and/or hot air movement.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWC	Draw D
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3. Document ID: US 20030051743 A1

L26: Entry 3 of 5

File: PGPB

Mar 20, 2003

PGPUB-DOCUMENT-NUMBER: 20030051743

PGPUB-FILING-TYPE: new

DOCUMENT-IDENTIFIER: US 20030051743 A1

TITLE: Apparatus and methods for removing metallic contamination from wafer containers

PUBLICATION-DATE: March 20, 2003

INVENTOR-INFORMATION:

NAME	CITY	STATE	COUNTRY	RULE-47
Breese, Ronald G.	Kalispell	MT	US	
Bryer, C. James	Kalispell	MT	US	
Bergman, Eric J.	Kalispell	MT	US	
Scranton, Dana R.	Kalispell	MT	US	

US-CL-CURRENT: 134/33; 134/103.2, 134/134, 134/140, 134/88

ABSTRACT:

In a method for cleaning for cleaning metallic ion contamination, and especially copper, from wafer containers, the containers are loaded into a loader of a cleaning apparatus. The containers are sprayed with a dilute chelating agent solution, while the rotor is spinning. The chelating agent solution removes metallic contamination from the containers. The containers are then sprayed with a rinsing liquid, such as deionized water and a surfactant while the rotor is spinning and heat is applied. The containers are then dried by applying heat, hot air movement and spinning the rotor.

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC	Draw D
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☐ 4. Document ID: US 5370919 A

L26: Entry 4 of 5

File: USPT

Dec 6, 1994

US-PAT-NO: 5370919

DOCUMENT-IDENTIFIER: US 5370919 A

**** See image for Certificate of Correction ****

TITLE: Fluorochemical water- and oil-repellant treating compositions

DATE-ISSUED: December 6, 1994

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Fleuws; Franceska	Brugge			BE
Allewaert; Kathy	Heverlee			BE
Coppens; Dirk	Antwerpen			BE

US-CL-CURRENT: 428/96; 106/2, 427/387, 427/389, 427/393.4, 427/394, 427/396,
428/361, 428/375, 428/421, 428/473, 428/537.5, 442/80, 442/94

ABSTRACT:

This invention relates to a treating composition containing 0.3 to 30% by weight of a fluoroaliphatic radical containing poly(oxyalkylene) compound, 0.3 to 30% by weight of an anti-soiling agent and 0 to 60% by weight of an environmentally acceptable water-miscible organic solvent and water for the use for imparting excellent water- and oil repellency, stain resistance and dry soil resistance to textiles, carpets, concrete, paper, leather and wool.

11 Claims, 0 Drawing figures

Exemplary Claim Number: 1

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KWIC	Draw D
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☐ 5. Document ID: US 20030051743 A1

L26: Entry 5 of 5

File: DWPI

Mar 20, 2003

DERWENT-ACC-NO: 2003-380804

DERWENT-WEEK: 200432

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TITLE: Metal removal method for wafer container, involves spraying chelating agent and rinsing liquid sequentially along rotating container and then container is dried

INVENTOR: BERGMAN, E J; BREESE, R G ; BRYER, C J ; SCRANTON, D R

PRIORITY-DATA: 2002US-0200071 (July 19, 2002), 2000US-0658395 (September 8, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
US 20030051743 A1	March 20, 2003		010	B08B007/00

INT-CL (IPC): B08 B 7/00

Full	Title	Citation	Front	Review	Classification	Date	Reference			Claims	KUIC	Draw De
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Term	Documents
METALLIC	963177
METALLICS	1889
CONTAMINATION	304161
CONTAMINATIONS	6446
(24 AND (METALLIC ADJ CONTAMINATION)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	5
(L24 AND (METALLIC CONTAMINATION)).PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD.	5

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